

Product Change Notice (PCN)

Subject: Package assembly site addition for RZ/A1L (208pinLQFP)

Publication Date: 6/23/2025

Effective Date: 1/7/2026

Revision Descriptions: Initial release

Change Descriptions:

Renesas will add an assembly site for RZ/A1L (208pinLQFP) to realize stable supply.

The Booking part numbers will be changed for identification because a part of package outline will also be changed from the current product.

In addition, at the additional assembly site, The Storage Conditions After Opening Moisture-Proof Packing will be changed from Humidity \leq 70%RH to Humidity \leq 60%RH.

Table:

Items	Additional site	Current site
Company	Y	Х
Location	Taiwan	Japan

Affected Product List:

Added products	Current products
R7S721021VCFP#AA2	R7S721021VCFP#AA1
R7S721021VCFP#BA2	R7S721021VCFP#BA1

Reason for Changes:

For stable supply of the product.

Impact on Fit, Form, Function, Quality & Reliability:

- Form : Drawings of the current product and additional product are shown in the appendix. Package outline is considered equivalent.
- Fit: No ImpactFunction: No ImpactQuality: No ImpactReliability: No Impact

Product Identification:

These products can be identified by package marking and packing label. (Refer to Appendix)

Qualification Status:

Now Available

Sample Availability Date:

7/31/2025

Device Material Declaration:

Please contact Renesas sales representatives.

RENESAS

PCN#:[EPPO-EX-25-0019-1]

Note:

- 1. Acknowledgement must be received by Renesas within 30 days or Renesas will consider the change as approved.
- If timely acknowledgement is provided by Customer, then Customer shall have 90 days from the date of receipt of this PCN to make any objections to this PCN. If Customer fails to make objections to this PCN within 90 days of the receipt of the PCN then Renesas will consider the PCN changes as approved.
- 3. If customer cannot accept the PCN then customer must provide Renesas with a last time buy demand and purchase order.

For additional information regarding this notice, please contact your Renesas sales representative.

Appendix

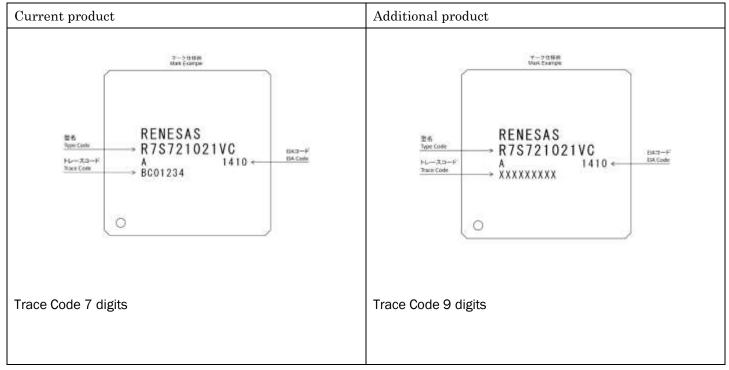
Package outline:

Current prod	uct			Additional pro	oduct		
Reference		<u>ņ in Mill</u>		Reference	Dimensio	n in Mill	imators
Symbol	Min.	Nom.	Max.	Symbol	Min.	Nom.	Max.
Α	_	-	1.7			<u> </u>	1.7
A1	0.05	0.1	0.15	A A1	0.05	_	
A2	-	1.4	-	A1 A2			0.15
HD	29.8	30	30. 2	D	1.35	1.4	1.45
D	-	28	-			30 BSC.	
HE	29.8	30	30.2	<u>D1</u> E		28 BSC.	
E	-	28	-	E E1		30 BSC.	
е	-	0.5	-			28 BSC.	
b	0.17	0. 22	0. 27	Ν		208	—
С	0.095	0. 145	0.195	e	0.17	0.5 BSC.	0.07
θ	0°	-	8°	b	0.17	0. 22	0.27
L	0.35	0.5	0.65	C	0.095	— •	0.195
L1	_	1.00	-	q	0°	3.5°	8°
b1	_	0. 2	-		0.35	0.5	0.65
c1	_	0.125	-	<u>L1</u>		<u>1.00 REF.</u>	0.0
х	_	-	0.08	<u>aaa</u>			0.2
y	_	-	0.08	bbb			0.2
ZD	_	1.25	-	ccc		-	0.08
ZE	_	1.25	-	ddd	_	—	0.08
Compliant (1.23		Compliant J	EDEC		

Storage Conditions After Opening Moisture-Proof Packing:

Current product	Additional product
Storage after opening moisture-proof packing	Storage after opening moisture-proof packing
Temperature 5-30°C	Temperature 5-30°C
Humidity ≦70%RH	Humidity ≦60%RH
Time ≦168 hours	Time ≤ 168 hours
	There is no change to Temperature and Time.

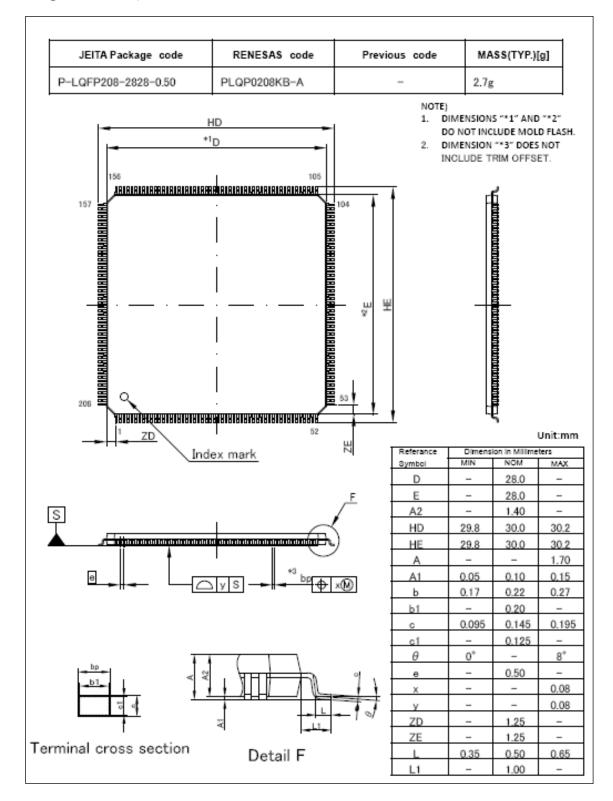
Package marking:



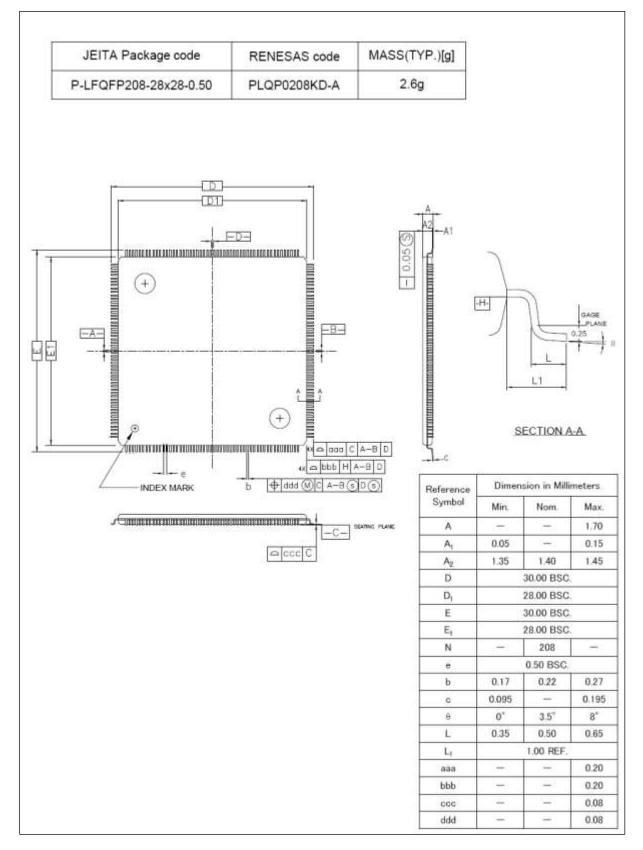
Packing label:

Current product	Additional product
D/N: R7S721021VCFP AA1WM02000 SPN: R7S721021VCFP#AA1 AA1WM02000	D/N: R7S721021VCFP AA2M508000 SPN: R7S721021VCFP#AA2 AA2M508000
	SPN order part number, The 17th digit from the left is "2".

Outline Drawing for current product:



Outline Drawing for additional product:



Storage Conditions After Opening Moisture-Proof Packing for current product:

実装条件 Mount Conditions RDK-J-000062-2 1/1 防湿包装開封後保管条件 ルネサス エレクトロニクス株式会 Storage Conditions After Opening Renesas Electronics Corporat 防湿包装開封後の保管について Storage after opening moisture-proof packing. 防湿包装開封後はパッケージの吸湿を避けるため、下記条件にて保管してください。 After opening moisture-proof packing, semiconductor devices must be stored under the following Monditions to prevent moisture absorption by the packages. 項目 条件 備考 Ltem Condition 温度 5°C~30°C 工emperature 5 - 30°C
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Item Condition Note 温度 5°C~30°C
温度 5°C~30°C
Temperature 5 - 30°C
湿度 70%RH 以下
Humidity ≦70%RH
時間 ※ 168 時間以内 Time ≦168 hours ※開封後~最終リフローはんだ付け完了ま での時間 The time from the point the packaging is opened until the last device reflowing has been completed.

Storage Conditions After Opening Moisture-Proof Packing for additional product:

fter opening moisture-proof packing, semiconductor devices must be stored under the following onditions to prevent moisture absorption by the packages. <u>項目 条件 備考</u> <u>Item Condition Note</u> <u>温度 5°C~30°C</u> <u>Temperature 5 - 30°C</u> <u>湿度 60%RH 以下</u> <u>Humidity ≦60%RH</u> 時間 ※ 168 時間以内 <u>Time 168 hours</u> <u>168 hours</u>	binditions to prevent moisture absorption by the packages.	う湿包装開封後はパ	ッケージの吸湿を避け	るため、下記条件にて保管してください。
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been completed.	been completed.			での時間 The time from the point the packaging is opened until the last device reflowing has
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